

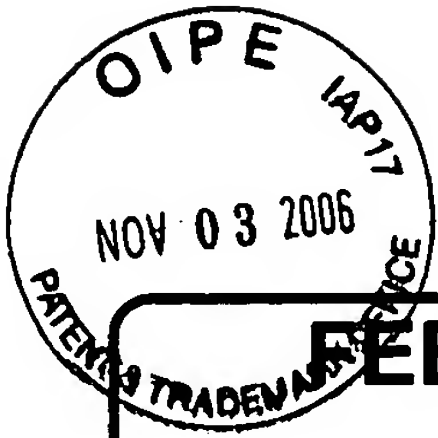
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|---|----------------------|------------------------|----------|
| <b>TRANSMITTAL FORM</b><br>(to be used for all correspondence after initial filing) | Application No.      | 10/608,718             |          |
|   | Filing Date          | June 27, 2003          |          |
|   | First Named Inventor | Richard D. Emery       |          |
|   | Art Unit             | 2814                   |          |
|   | Examiner Name        | Dilinh P. Nguyen       |          |
| Total Number of Pages in This Submission  |                      | Attorney Docket Number | 42P16889 |

| ENCLOSURES (check all that apply)  |   |  |
|--|---|--|
| <input checked="" type="checkbox"/> Fee Transmittal Form<br><br><input type="checkbox"/> Fee Attached<br><br><input checked="" type="checkbox"/> Amendment / Reply<br><br><input type="checkbox"/> After Final<br><input type="checkbox"/> Affidavits/declaration(s)<br><br><input type="checkbox"/> Extension of Time Request<br><br><input type="checkbox"/> Express Abandonment Request<br><br><input type="checkbox"/> Information Disclosure Statement<br><br><input type="checkbox"/> PTO/SB/08<br><br><input type="checkbox"/> Certified Copy of Priority Document(s)<br><br><input type="checkbox"/> Response to Missing Parts/Incomplete Application<br><br><input type="checkbox"/> Basic Filing Fee<br><input type="checkbox"/> Declaration/POA<br><br><input type="checkbox"/> Response to Missing Parts under 37 CFR 1.52 or 1.53 | <input type="checkbox"/> Drawing(s)<br><br><input type="checkbox"/> Licensing-related Papers<br><br><input type="checkbox"/> Petition<br><br><input type="checkbox"/> Petition to Convert a Provisional Application<br><br><input type="checkbox"/> Power of Attorney, Revocation Change of Correspondence Address<br><br><input type="checkbox"/> Terminal Disclaimer<br><br><input type="checkbox"/> Request for Refund<br><br><input type="checkbox"/> CD, Number of CD(s)<br><br><input type="checkbox"/> Landscape Table on CD | <input type="checkbox"/> After Allowance Communication to TC<br><br><input checked="" type="checkbox"/> Appeal Communication to Board of Appeals and Interferences<br><br><input type="checkbox"/> Appeal Communication to TC (Appeal Notice, Brief, Reply Brief)<br><br><input type="checkbox"/> Proprietary Information<br><br><input type="checkbox"/> Status Letter<br><br><input checked="" type="checkbox"/> Other Enclosure(s) (please identify below):<br><div style="border: 1px solid black; height: 80px; margin-top: 10px;"></div> |
| Remarks  |   |  |

| SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT |   |
|--|---|
| Firm or Individual name                    | Mark C. Van Ness, Reg. No. 39,865<br>BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP |
| Signature                                  |   |
| Date                                       | October 31, 2006  |

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| Typed or printed name   | Mark C. Van Ness |      |                  |
| Signature   |                  | Date | October 31, 2006 |



# FEE TRANSMITTAL for FY 2005

Patent fees are subject to annual revision.

☐ Applicant claims small entity status. See 37 CFR 1.27.

TOTAL AMOUNT OF PAYMENT

(\$)

## Complete if Known

|                      |                  |
|----------------------|------------------|
| Application Number   | 10/608,718       |
| Filing Date          | June 27, 2003    |
| First Named Inventor | Richard D. Emery |
| Examiner Name        | Dilinh P. Nguyen |
| Art Unit             | 2814             |
| Attorney Docket No.  | 42P16889         |

## METHOD OF PAYMENT (check all that apply)

☐ Check ☐ Credit card ☐ Money Order ☒ None ☐ Other (please identify): \_\_\_\_\_

☒ Deposit Account Deposit Account Number: 02-2666 Deposit Account Name: Blakely, Sokoloff, Taylor & Zafman LLP

For the above-identified deposit account, the Director is hereby authorized to: (check all that apply)

☐ Charge fee(s) indicated below ☐ Charge fee(s) indicated below, except for the filing fee  
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## FEE CALCULATION

| Large Entity              |          | Small Entity |          | Fee Description  | Fee Paid |
|---------------------------|----------|--------------|----------|--|----------|
| Fee Code                  | Fee (\$) | Fee Code     | Fee (\$) |  |          |
| 1051                      | 130      | 2051         | 65       | Surcharge - late filing fee or oath                              |          |
| 1052                      | 50       | 2052         | 25       | Surcharge - late provisional filing fee or cover sheet.          |          |
| 2053                      | 130      | 2053         | 130      | Non-English specification  |          |
| 1251                      | 120      | 2251         | 60       | Extension for reply within first month                           |          |
| 1252                      | 450      | 2252         | 225      | Extension for reply within second month                          |          |
| 1253                      | 1,020    | 2253         | 510      | Extension for reply within third month                           |          |
| 1254                      | 1,590    | 2254         | 795      | Extension for reply within fourth month                          |          |
| 1255                      | 2,160    | 2255         | 1,080    | Extension for reply within fifth month                           |          |
| 1401                      | 500      | 2401         | 250      | Notice of Appeal   |          |
| 1402                      | 500      | 2402         | 250      | Filing a brief in support of an appeal                           |          |
| 1403                      | 1,000    | 2403         | 500      | Request for oral hearing   |          |
| 1451                      | 1,510    | 2451         | 1,510    | Petition to institute a public use proceeding                    |          |
| 1460                      | 130      | 2460         | 130      | Petitions to the Commissioner                                    |          |
| 1807                      | 50       | 1807         | 50       | Processing fee under 37 CFR 1.17(q)                              |          |
| 1806                      | 180      | 1806         | 180      | Submission of Information Disclosure Stmt                        |          |
| 1809                      | 790      | 1809         | 395      | Filing a submission after final rejection (37 CFR § 1.129(a))    |          |
| 1810                      | 790      | 2810         | 395      | For each additional invention to be examined (37 CFR § 1.129(b)) |          |
| Other fee (specify) _____ |          |              |          |  |          |
| SUBTOTAL (2)              |          |              |          |  | (\$)     |

## SUBMITTED BY

## Complete (if applicable)

|                   |                  |                                      |          |           |                |
|-------------------|------------------|--------------------------------------|----------|-----------|----------------|
| Name (Print/Type) | Mark C. Van Ness | Registration No.<br>(Attorney/Agent) | 39,865   | Telephone | (503) 439-8778 |
| Signature         |                  | Date                                 | 10/31/06 |           |                |



Our Docket No.: 42P16889

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: )

Richard D. Emery )

Application No: 10/608,718 )

Filed: June 27, 2003 )

For: Fabrication of Microelectronic Devices )

Examiner: NGUYEN, DILINH

Art Unit: 2814

Mail Stop Appeal  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**APPEAL BRIEF**  
**IN SUPPORT OF APPELLANT'S APPEAL**

Sir or Madam:

Appellant hereby submits this Brief in support of its appeal from an Office Action by the Examiner, mailed May 31, 2006, in the above-referenced Application. Appellant respectfully requests consideration of this appeal and the allowance of the above-captioned patent application.

An oral hearing is not requested.

FIRST CLASS CERTIFICATE OF MAILING

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Date of Deposit: 10/31/06

Name of Person Mailing Correspondence: Mark C. Van Ness

Signature

Date

## TABLE OF CONTENTS

|        |  |           |
|--------|--|-----------|
| (i)    | REAL PARTY IN INTEREST .....   | 3         |
| (ii)   | RELATED APPEALS AND INTERFERENCES.....   | 3         |
| (iii)  | STATUS OF CLAIMS .....   | 3         |
| (iv)   | STATUS OF AMENDMENTS .....   | 5         |
| (v)    | SUMMARY OF CLAIMED SUBJECT MATTER .....  | 6         |
| (vi)   | GROUND OF REJECTION TO BE REVIEWED ON APPEAL .....   | 8         |
| (vii)  | ARGUMENT .....   | 9         |
|        | (a) <u>The thermal conduction element provided in <i>Horvath</i> is not relevant to</u><br><u>the claims</u> ..... | 9         |
|        | (b) <u>The packaging for thermal conduction provided <i>Lee</i> is not relevant to</u><br><u>the claims</u> .....  | 11        |
|        | (c) <u>The thermal transfer plate provided in <i>Turner</i> is not relevant to the</u><br><u>claims</u> .....      | 12        |
|        | (d) <u>The heat spreader provided in <i>Zhang</i> is not relevant to the claims</u> .....                          | 13        |
| (viii) | CLAIMS APPENDIX.....   | <u>16</u> |
| (ix)   | EVIDENCE APPENDIX.....   | 19        |
| (x)    | RELATED PROCEEDINGS APPENDIX .....   | 19        |

(i) **REAL PARTY IN INTEREST**

The invention is assigned to Intel Corporation of 2200 Mission College Boulevard, Santa Clara, California 95052.

(ii) **RELATED APPEALS AND INTERFERENCES**

To the best of Appellant's knowledge, there are no appeals, interferences, or judicial proceedings related to the present appeal that are related to, will directly affect, will be directly affected by, or will have a bearing on the Board's decision.

(iii) **STATUS OF THE CLAIMS**

Claims 1, 3-10, and 31-37 are currently pending in the above-referenced application, with claims 2 and 11-30 being canceled. In the Office Action mailed May 31, 2006, claims 1, 3, 4, and 6-10 were rejected, 5 was objected to, and claims 31-37 were allowed.

Claims 1 and 6 are rejected under 35 U.S.C. §102 (e) as being anticipated by U.S. Patent No. 4,415,025 of Horvath (hereinafter referred to as *Horvath*).

Claims 1, 4, and 6 are rejected under 35 U.S.C. §102 (e) as being anticipated by U.S. Patent No. 6,081,037 of Lee, et al. (hereinafter referred to as *Lee*).

Claims 1 and 6 are rejected under 35 U.S.C. §102 (e) as being anticipated by U.S. Patent Application Publication No. 2002/0185728 of Turner (hereinafter referred to as *Turner*).

Claims 3 and 7-10 are rejected under 35 U.S.C. §103 (a) as being unpatentable over *Horvath*, *Lee*, or *Turner* in view of U.S. Patent Application Publication No. 2002/0171144 of Zhang, et al. (hereinafter referred to as *Zhang*).

The Examiner has objected to claim 5 as being dependent upon a rejected base claim. The Examiner has objected to claims 4, 6, and 31 because of informalities in the claims. The informalities are addressed in a pending amendment, but it is submitted that allowance of the amendments is not necessary for consideration of the current appeal.

**(iv) STATUS OF AMENDMENTS**

An amendment to the claims has been filed solely to incorporate wording changes requested by the Examiner in claims 4 and 31 to correct informalities in the claims.

Applicant is requesting the entry of this amendment.

However, it is submitted that the current claims without entry of the amendments are clear for appeal, and thus the amendments are not required for purposes of the appeal, if it is determined that the amendment is not proper at this time. The only changes suggested are changing “the plate” to “the first plate” in claims 4 and 31. The relevant claims only refer to the first plate, and thus the meaning of the claims is clear. (The claims presented in the Appendix are the current claims, without entry of this amendment.)

Appellants filed a timely Notice of Appeal on August 31, 2006. The Notice of Appeal was in the form of a reinstatement of the prior appeal in this matter.

(v) **SUMMARY OF THE CLAIMED SUBJECT MATTER**

The present invention generally relates to microelectronic devices, and specifically to a microelectronic device that affects expansion characteristics. (See Field of the Invention, ¶ 0001).

An embodiment of the invention may be understood by referring to Figures 2 and 3 and the supporting text of the specification. In Figure 2, a package 200 is illustrated, with the package including solder bumps 220 to provide a connection to the die 240. The package 200 may include a first plate 225, which in this instance surrounds the die 240. In this illustration, the first plate 225 is coupled with the die 240 by a material, such as a stiff solder, that provides a secure physical connection. (See Description, ¶0028) In this illustration, the first plate 225 modifies the apparent coefficient of thermal expansion. In one example, as temperatures increase and the first plate 235 expands, the die 235 is forced to expand by the forces pulling on the die 235 at the points of attachment between the die 235 and the first plate 225 on the edges of the die 235. The package may also include a second plate 230 that is coupled with the package 200 by an adhesive, with the connection to the second plate modifying the coefficient of thermal expansion of the package. (See Description, ¶0029)

Figure 3 then illustrates an embodiment of the invention that includes a package 300 again with a die 340. In this embodiment of the invention, a first plate 325 is coupled with the die 340, in this instance is coupled with one side (such as the inactive side) of the die 340. The coupling is accomplished using a material providing a strong connection to the die, such as a stiff solder. A second plate 330 may also be attached to the package 300, such as by an adhesive. (See Description, ¶0030)



In Figures 2 and 3, the first plate and the second plate are constructed of materials that are chosen to match the apparent coefficient of thermal expansion of a die with the coefficient of thermal expansion of a package. (See Description, ¶0031)

(vi) **GROUND OF REJECTION TO BE REVIEWED ON APPEAL**

Claims 1 and 6 are rejected under 35 U.S.C. §102 (e) as being anticipated by U.S. Patent No. 4,415,025 of Horvath (hereinafter referred to as *Horvath*).

Claims 1, 4, and 6 are rejected under 35 U.S.C. §102 (e) as being anticipated by U.S. Patent No. 6,081,037 of Lee (hereinafter referred to as *Lee*).

Claims 1 and 6 are rejected under 35 U.S.C. §102 (e) as being anticipated by U.S. Patent Application Publication No. 2002/0185728 of Turner (hereinafter referred to as *Turner*).

Claims 3 and 7-10 are rejected under 35 U.S.C. §103 (a) as being unpatentable over *Horvath*, *Lee*, or *Turner* in view of U.S. Patent Application Publication No. 2002/0171144 of Zhang, et al. (hereinafter referred to as *Zhang*).

The Examiner has objected to claim 5 as being dependent upon a rejected base claim, and such claim would be allowable if the base claim is allowed.

Claims 31-37 have been allowed and are not the subject of this appeal.

(vii) **ARGUMENT**

The Examiner has rejected the claims under various references. It is submitted that numerous references that are not relevant to the claims have been cited in the multiple office actions in this matter. When the Applicant has disposed of a reference in a response, more references of the same type have been cited. In particular, the references cited generally refer to the subject of heat dissipation, which is not relevant to the claims.

In order to bring this process to a conclusion, the Applicant by this appeal wishes to demonstrate that the cited references, and any other references of this same type, do not teach or suggest the elements of the claims presented.

(a) The thermal conduction element provided in *Horvath* is not relevant to the claims

The Examiner rejected claims 1 and 6 under 35 U.S.C. 102(e) as being anticipated by *Horvath*. Appellant respectfully submits that such claims are not anticipated by the reference, and that the claims should be allowed.

**Claim 1**

Independent claim 1 reads as follows:

1. A microelectronic device comprising:  
a die, the die comprising a first side, a second side, and an edge;  
a first plate, the first plate coupled with the die, the first plate exerting force on the die to modify the effective coefficient of thermal expansion of the die; and  
a package, the die being coupled with the package.

This claim includes a first plate, with “the first plate exerting force on the die to modify the effective coefficient of thermal expansion of the die”. It is respectfully

submitted that none of cited references teaches or suggests this claim element. The cited references do not address a plate exerting force on a die to modify the effective coefficient of thermal expansion of the die.

Appellant respectfully submits that *Horvath* does not anticipate this element of the claim. *Horvath* addresses a thermal conduction element for semiconductor devices, which is not relevant to exertion of force on a die. The conduction of heat away from a die does not exert force on the die. Further, the conduction of heat does not modify the effective coefficient of thermal expansion of a die, but rather reduces the heat applied to a die. The reduction of heat may reduce expansion, but does not modify the effective coefficient of thermal expansion.

As shown in Figure 1 of *Horvath*, the element in question is a disk shaped thermal bridge that is intended to conduct from a device to a cold plate. As stated in *Horvath*, the claimed invention is a conduction element for cooling semiconductors. “The invention is an improved cooling element adapted to be positioned between a solder bonded semiconductor device and a module cap or cold plate to form a heat conduction bridge between the device and the cap or cold plate.” (*Horvath*, col. 2, lines 38-40)

The operation of the device in *Horvath* is further shown by an examination of the structure illustrated in Figures 1 and 3. As illustrated, a semiconductor (also referred to as device) 12 is connected to a substrate 10 by solder connections, and is connected to a thermal element 24, which conducts heat to a cap 16. The connection is in the form of a coating 32 (as shown in Figure 3) of a low melting alloy, preferably lead (Pb). (*Horvath*, col. 4, lines 24-33) An alternative is a thin layer of thermal grease. (*Horvath*, col. 4, lines 38-40) It is apparent from such construction that the issue involved is the conduct of heat, and not exertion of force. The use of a lead alloy or grease does not appear to

provide a conduct that would allow any exertion of force. The only mention of force appears to be a very different issue, which is the construct of slots on the thermal element in a manner that will not exert too much force on the semiconductor. “The number of slots and the length relative to the diameter of the element is dictated by the thickness of the disk and also the permissible force that can be exerted on semiconductor 12.”

(*Horvath*, col. 3, lines 50-54)

Thus rather than address a force exerted to modify the coefficient of thermal expansion, Horvath has provided an apparatus for conducting heat away from a semiconductor device. Thus, *Horvath* has also chosen a very different approach to addressing thermal expansion, and this reference has no relation to the elements of the claims that are at issue here. As stated previously, conducting heat away simply cools a device – it does not modify its coefficient of thermal expansion. Thus, it is submitted that Horvath does not address modification of a coefficient of thermal expansion.

(b) The packaging for thermal conduction provided *Lee* is not relevant to the claims

The Examiner rejected claims 1, 4, and 6 under 35 U.S.C. 102(e) as being anticipated by *Lee*. Appellant respectfully submits that such claims are not anticipated by the reference, and that the claims should be allowed.

*Lee* relates to a semiconductor component having a semiconductor chip mounted to a chip mount. However, there is no indication in *Lee* of any teaching or suggestion of a plate that is to exert a force to on a die to modify the effective coefficient of thermal expansion of the die.

*Lee* is intended to provide “a method for packaging a semiconductor chip into a semiconductor device that has a superior thermal performance.” (*Lee*, col. 1, lines 52-54)

The intent of such package is conduction of heat, not the exertion of force to modify a coefficient of thermal expansion. “A thermally conductive chip mount has a chip receiving area thermally coupled to the chip. The heat generated in the chip can dissipate to the chip mount through the sides of the chip. Compared with a conventional heat sink mounted on the back side of a flip chip, the chip mount of the present invention has a low profile.” (*Lee*, col. 1, lines 60-65)

Thus, again *Lee* is concerned with heat conduction, and not with the exertion of force on a die to modify the effective thermal coefficient of expansion.

(c) The thermal transfer plate provided in *Turner* is not relevant to the claims

The Examiner rejected claims 1 and 6 under 35 U.S.C. 102(e) as being anticipated by *Turner*. Appellant respectfully submits that such claims are not anticipated by the reference, and that the claims should be allowed.

*Turner* addresses a thermal transfer plate for coupling a thermal hardware element to an integrated circuit package. The plate presented in *Turner* is of a particular design that may be mounted in such a way as to address tolerance issues. Each footpad includes a spring zone 36 and a standoff member 40. As described in *Turner*, the standoff members and footpads are connected to the plate via the spring zones, which permit depression of the footpads towards the substrate during installation. (*Turner*, ¶0017) The intent of the design is to provide that force caused by, for example, dropping the product is transferred to the substrate without disturbing the position of the plate. Further, the design is intended to compensate for tolerance variations. (*Turner*, ¶0018)

Thus, rather than address a physical force to thermal expansion, *Turner* has provided an apparatus for attaching a thermal plate, which then would conduct heat away

from a device. In this case, *Turner* is not actually concerned with thermal expansion at all. Rather, *Turner* is concerned with a method of attaching a thermal plate in a spring-loaded fashion that will withstand dropping and reduce tolerance issues.

Thus, *Turner* does not address the exertion of force on a die to modify the effective coefficient of thermal expansion.

### **Other Claims**

The remaining rejected claims rejected as being anticipated by *Horvath*, *Lee* or *Turner*, claims 4 and 6, while having other differences, are dependent claims and are allowable as being dependent on the allowable base claim. Appellant respectfully submits that absent any suggestion in this or any other reference of record, the respective claims are not anticipated.

#### **(d) The heat spreader provided in *Zhang* is not relevant to the claims**

Claims 3 and 7-10 are rejected under 35 U.S.C. §103 (a) as being unpatentable over *Horvath*, *Lee*, or *Turner* in view of *Zhang*.

Claims 3 and 7-10, while having other differences, are dependent claims and are allowable as being dependent on the allowable base claim.

*Horvath*, *Lee* and *Turner* are discussed above. It is submitted that *Zhang* does not teach or suggest the claim element missing from the other references, and thus any combination of the references thus cannot teach or suggest the elements of the independent claim.

It is submitted that *Zhang* does not provide for a plate exerting forces on a die to modify its effective coefficient of thermal expansion. *Zhang* describes a grid array package with a heat spreader. (*Zhang*, e.g. ¶0002) The head spreader is intended to

improve the thermal and electrical performance of a package. (Zhang, ¶¶0013, 0053)

*Zhang* is concerned with thermal and electrical performance, not with affecting the coefficient of thermal expansion of the die.

*Zhang* does mention mentions coefficient of thermal expansion in paragraph 0065, but in a completely different context:

[0065] In an embodiment, stiffener or ring 502 is attached to the top surface of substrate 104. Ring 502 may be attached to substrate 104 by a laminate or adhesive 510. Encapsulant 116 is filled in and flushed to ring 502 after the attachment of ring 502. Ring 502 is preferably made of a metal, such as copper or aluminum, or a combination thereof, but may also be constructed from other applicable materials. *Preferably, ring 502 is made from the same material as heat spreader 504, to minimize the mismatch of the thermal expansion coefficients.* Ring 502 is preferably flush with the outer edges of substrate 104 to form an outer edge of the BGA package, but may also reside entirely within or partially outside an outer profile of substrate 104.

(emphasis added) *Zhang* is indicating that a ring 502 may be attached to the top surface of the substrate, and that it is preferable to match the coefficient of thermal expansion of the ring and the heat spreader. Therefore, *Zhang* is only suggesting that the coefficient of thermal expansion values of these structures that are added to the die should match. It is thus submitted that the provisions in *Zhang* have no relevance to the coefficient of thermal expansion of the die.



## **CONCLUSION**

Careful review of the Examiner's rejections shows that the Examiner has failed to provide any reference or combination of references that shows the claims. Therefore, Appellant respectfully submits that all appealed claims in this application are patentable and were improperly rejected by the Examiner during prosecution before the United States Patent and Trademark Office. Appellant respectfully requests that the Board of Patent Appeals and Interferences reverse the Examiner and direct allowance of the rejected claims.

Because this is a resubmittal of a brief in a reopened appeal, it is Applicant's understanding that no fee for the filing of the brief is due. Please charge any shortages and credit any overcharges to our Deposit Account No. 02-2666.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

Dated: October 31, 2006



Mark C. Van Ness  
Reg. No. 39,865

12400 Wilshire Boulevard  
Seventh Floor  
Los Angeles, CA. 90025-1030  
(303) 740-1980

**(viii) CLAIMS APPENDIX**

*The claims on appeal read as follows. (The claims herein do not include claim modifications suggested in the amendment currently pending.)*

1. A microelectronic device comprising:  
a die, the die comprising a first side, a second side, and an edge;  
a first plate, the first plate coupled with the die, the first plate exerting force on the die to modify the effective coefficient of thermal expansion of the die; and  
a package, the die being coupled with the package.
2. (Cancelled)
3. The microelectronic device of claim 1, where the first plate modifies the coefficient of thermal expansion of the die to make the coefficient of thermal expansion of die more closely match the coefficient of thermal expansion of the package.
4. The microelectronic device of claim 1, wherein the first plate comprises a hole, the die fitting within the hole, the edge of the die being coupled with an edge of the plate by the hole.
5. The microelectronic device of claim 4, wherein the edge of the die is soldered with the edge of the first plate.
6. The microelectronic device of claim 1, wherein a side of the die is coupled with a side of the first plate.
7. The microelectronic device of claim 1, further comprising a second plate coupled

with the package.

8. The microelectronic device of claim 7, wherein the package is attached with the second plate by an adhesive.
9. The microelectronic device of claim 7, wherein the first plate and second plate are constructed of the same material.
10. The microelectronic device of claim 9, wherein the first plate and the second plate are constructed of copper.
- 11-30. (Cancelled)
31. A microelectronic device comprising:  
a die, the die comprising a first side, a second side, and an edge;  
a first plate, the first plate coupled with the die, the first plate comprising a hole,  
the die fitting within the hole, the edge of the die being coupled with an  
edge of the plate by the hole, the edge of the die being soldered with the  
edge of the first plate; and  
a package, the die being coupled with the package.
32. The microelectronic device of claim 31, wherein the first plate exerts forces on the die to modify its effective coefficient of thermal expansion.
33. The microelectronic device of claim 32, where the first plate modifies the coefficient of thermal expansion of the die to make the coefficient of thermal expansion of die more closely match the coefficient of thermal expansion of the package.

34. The microelectronic device of claim 31, further comprising a second plate coupled with the package.
35. The microelectronic device of claim 34, wherein the package is attached with the second plate by an adhesive.
36. The microelectronic device of claim 35, wherein the first plate and second plate are constructed of the same material.
37. The microelectronic device of claim 36, wherein the first plate and the second plate are constructed of copper.

**(ix) EVIDENCE APPENDIX**

None.

**(x) RELATED PROCEEDINGS APPENDIX**

None.